PRODUCT/PRODUCT CATEGORY/SERVICE	Which data are being collected (type, format and expected volume)	Time frame (continuously, realtime etc)	Where is the data stored	Duration of retention	How can it be accessed?	How the user may erase the data
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] <Detailed items are below>	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ProcessStatusReport.MACHINE_STATUS, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ControlStatusReport.Control status, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] AlarmListReport.Alarm Set, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ProcessProgramReport <Detailed items are below>	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ProcessProgramReport.MODEL_ID, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ProcessProgramReport.MODEL_NAME, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ProcessProgramReport.WORK_ID, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ProcessProgramReport.PP_ID, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ProcessProgramReport, LOT_NUMBER, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ProcessProgramReport.OPERATOR_ID, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] SpoolinActive.Clock, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] MessageCheckReport.Terminal ID, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] DiePickupReport <Detailed items are below>	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] DiePickupReport.XAXIS, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] DiePickupReport.YAXIS, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] DiePickupReport.MATERIAL_ID, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] DiePickupReport.FLAT_NOTCH, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console

PRODUCT/PRODUCT CATEGORY/SERVICE	Which data are being collected (type, format and expected volume)	Time frame (continuously, realtime etc)	Where is the data stored	Duration of retention	How can it be accessed?	How the user may erase the data
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] SubstrateMapReport.SUBSTRATE_MAP_DATA, string list	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] MeaterialChangeReport <Detailed items are below>	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] MeaterialChangeReport.WAFER_INDEXNO, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] MeaterialChangeReport.MATERIAL_ID, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend <Detailed items are below>	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA001, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA002, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA003, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA004, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA005, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA006, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA007, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA008, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA009, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA010, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA011, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA012, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA013, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA014, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console

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MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA015, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA016, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA017, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA018, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA019, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA020, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA021, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA022, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA023, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA024, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA025, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA026, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA027, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA028, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA029, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA030, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA031, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA032, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA033, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console

PRODUCT/PRODUCT CATEGORY/SERVICE	Which data are being collected (type, format and expected volume)	Time frame (continuously, realtime etc)	Where is the data stored	Duration of retention	How can it be accessed?	How the user may erase the data
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA034, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA035, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA036, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA037, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA038, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA039, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA040, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA041, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA042, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA043, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA044, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA045, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA046, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA047, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA048, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA049, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA050, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA051, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA052, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console

PRODUCT/PRODUCT CATEGORY/SERVICE	Which data are being collected (type, format and expected volume)	Time frame (continuously, realtime etc)	Where is the data stored	Duration of retention	How can it be accessed?	How the user may erase the data
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA053, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA054, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA055, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA056, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] RecipeDataSend.RECIPE_PARA057, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ChipBondingReport <Detailed items are below>	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ChipBondingReport.BLOCK_NO, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ChipBondingReport.UNIT_NO, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ChipBondingReport.SEQ_NO, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ChipBondingReport.PARTS_NO, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ChipBondingReport.PICKEDUP_POSX, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ChipBondingReport.PICKEDUP_POSY, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ChipBondingReport.PICKEDUP_WAFERID, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ChipBondingReport.BONDING_FLAT_NOTCH, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ChipBondingMissReport <Detailed items are below>	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ChipBondingMissReport.BONDING_POSX, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[RPTID] ChipBondingMissReport.BONDING_POSY, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] <Detailed items are below> (SV class only)	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Control status, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console

PRODUCT/PRODUCT CATEGORY/SERVICE	Which data are being collected (type, format and expected volume)	Time frame (continuously, realtime etc)	Where is the data stored	Duration of retention	How can it be accessed?	How the user may erase the data
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Equipment status, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Equipment failure details, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Previous equipment status, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Previous equipment failure details, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Previous Control Status, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Clock, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Previous equipment electric power supply off time, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Set status alarm list, string list	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Effective alarm list, string list	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Down time code, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Down time text, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Down time data, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Effective event list, string list	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Equipment model, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Equipment name, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Equipment serial No., string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Software revision, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Establishment communication status, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Host communication status, numeric, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console

PRODUCT/PRODUCT CATEGORY/SERVICE	Which data are being collected (type, format and expected volume)	Time frame (continuously, realtime etc)	Where is the data stored	Duration of retention	How can it be accessed?	How the user may erase the data
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Host communication error code, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] communication stream function, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Equipment communication status, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Equipment communication error code, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] On-Line Confirm Enable/Disable, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Process Unit 1 Status, numeric, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Previous Process Unit 1 Status, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PPID_SEND, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PPID_UPLOAD_COMP, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] MODELID, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] MODEL_NAME, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WORD_ID, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PP_ID, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] MACHINE_STATUS, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] DEVICEID, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] LOT_NUMBER, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] OPERATOR_ID, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] OPERATOR_LEVEL, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] POWERDOWN_TIME, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console

PRODUCT/PRODUCT CATEGORY/SERVICE	Which data are being collected (type, format and expected volume)	Time frame (continuously, realtime etc)	Where is the data stored	Duration of retention	How can it be accessed?	How the user may erase the data
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] MODEL_CHG, numeric, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] _CHG, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] _FLAG, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] _STATUS1, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_STATUS2, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_STATUS3, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_STATUS4, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_STATUS5, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_STATUS6, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_STATUS7, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_STATUS8, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_STATUS9, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_STATUS10, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_ID1, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_ID2, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_ID3, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_ID4, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_ID5, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_ID6, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console

PRODUCT/PRODUCT CATEGORY/SERVICE	Which data are being collected (type, format and expected volume)	Time frame (continuously, realtime etc)	Where is the data stored	Duration of retention	How can it be accessed?	How the user may erase the data
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_ID7, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_ID8, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_ID9, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_ID10, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] DISPENCE_STATUS1, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] DISPENCE_STATUS2, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] DISPENCE_STATUS11, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] DISPENCE_STATUS12, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] EJECTOR_STATUS1, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] EJECTOR_STATUS2, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] INDEXNO, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] XAXIS, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] YAXIS, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] BIN_CODE, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] WAFER_INDEXNO, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] MATERIAL_ID, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] OUT_WAFER_INDEXNO, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] OUT_MATERIAL_ID, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] FLAT_NOTCH, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console

PRODUCT/PRODUCT CATEGORY/SERVICE	Which data are being collected (type, format and expected volume)	Time frame (continuously, realtime etc)	Where is the data stored	Duration of retention	How can it be accessed?	How the user may erase the data
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] BONDING.POSX, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] BONDING.POSY, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PICKEDUP.POSX, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PICKEDUP.POSY, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PICKEDUP.WAFERID, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] bonding Block number, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] bonding Unit number, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] bonding Sequence number, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] bonding Parts number, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] BONDING.FLAT.NOTCH, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_UNIQUEID1, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_UNIQUEID2, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_UNIQUEID3, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_UNIQUEID4, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_UNIQUEID5, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_UNIQUEID6, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_UNIQUEID7, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_UNIQUEID8, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_UNIQUEID9, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console

PRODUCT/PRODUCT CATEGORY/SERVICE	Which data are being collected (type, format and expected volume)	Time frame (continuously, realtime etc)	Where is the data stored	Duration of retention	How can it be accessed?	How the user may erase the data
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_UNIQUEID10, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_ID1, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_ID2, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_ID3, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_ID4, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_ID5, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_ID6, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_ID7, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_ID8, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_ID9, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_ID10, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PRODUCT_STATUS1, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PRODUCT_STATUS2, **numeric**	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PRODUCT_STATUS3, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PRODUCT_STATUS4, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PRODUCT_STATUS5, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PRODUCT_STATUS6, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PRODUCT_STATUS7, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PRODUCT_STATUS8, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console

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MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PRODUCT_STATUS9, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PRODUCT_STATUS10, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PROCESS_FLAG1, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PROCESS_FLAG2, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PROCESS_FLAG3, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_OUT_ID2, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] PANEL_OUT_ID3, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Operator shift date, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Operator shift time, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] running time, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] non connect time, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] affect flag, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Alarm Event happen date, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Alarm Event happen time, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Main alarm number, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Main alarm message, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] MTBF flag, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Sub alarm number, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Sub alarm message, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console

PRODUCT/PRODUCT CATEGORY/SERVICE	Which data are being collected (type, format and expected volume)	Time frame (continuously, realtime etc)	Where is the data stored	Duration of retention	How can it be accessed?	How the user may erase the data
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] alarm happen flag, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Process Event happen date, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Process Event happen time, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Process Panel ID, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Process Bonding time, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Wafer pick up chip count, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] Bonded chip count, numeric	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] DownloadedRecipeID, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[SVID] UploadedRecipeID, string	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console
MD-P series LinePC (Die Bonder and FlipChip Bonder Data Interface)	[DVID] <Detailed items are below> (DV class only)(Size 0 omitted)	When an Event occurs or when Requested by communication	Internal Storage	Standard 30Days or Up to storage apacity	Use GEM communication	Use Delete button on linePC console